

Immersion Gold

ENIG Process



TECHNIC

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TechniPad Au 6100 Techni IM Gold AT 8000

These two processes share the same Proprietary Substrate Catalysed Reaction technology. TechniPad AU 6100 is a cyanide base process while Techni IM Gold AT 8000 is a cyanide-free process.

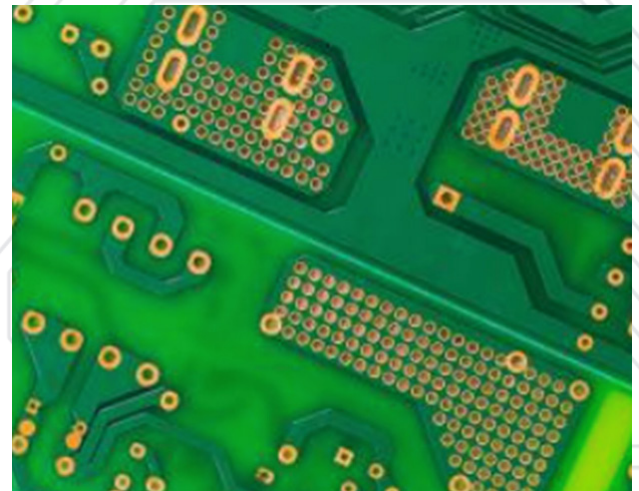
The substrate catalyzed reaction mechanism removes 75% less nickel than standard Immersion Gold process. While being less aggressive, the surface is better sealed. This unique mechanism, allow for better distribution with extremely low STD. This means, less Gold thickness variation, reduced cost and improved performance.

Features

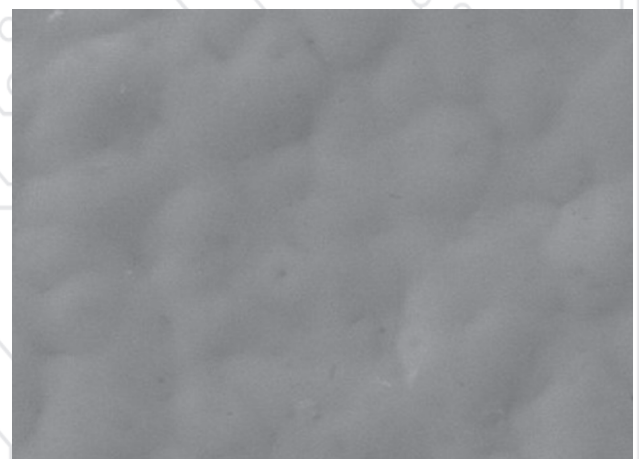
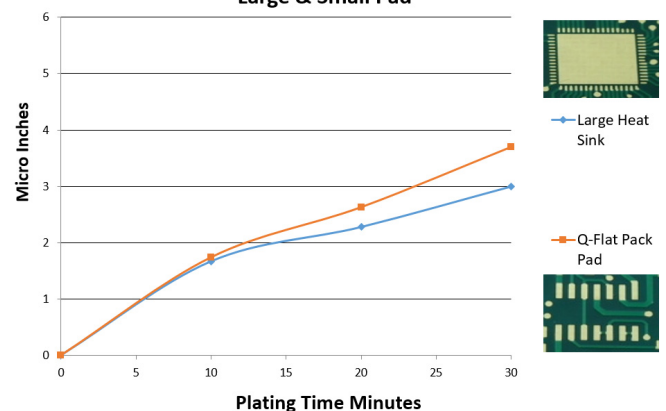
- Lowest cost on the market
- Easy to maintain
- Extreme long life, up to 20 MTO
- Smallest variation from pad to pad
- Does not discolor the white solder mask

Benefits

- Excellent distribution
- Uniform gold deposit
- Better sealed surface
- Eliminate corrosion
- Pass the IPC 4552 A and B spec
- Stable and extremely long life



AT8000 and AU6100 Plating Thickness
Large & Small Pad



Both our Immersion Gold baths combined with our Unique Electroless Nickel 5600, will deposit a flatter surface with a thin layer of sealed Gold for enhanced performance and reduced cost.

Advance Immersion Gold

ENEPIG Process

Technipad AU 6100

- Cyanide base process
- Up to 20 MTO bath life
- Reduced Nickel attack by 75%
- Sealed the surface and help balance thickness variation
- No Discoloration of white Solder Mask
- Minimal STD from pad to pad for enhanced cost and performance
- Self limiting

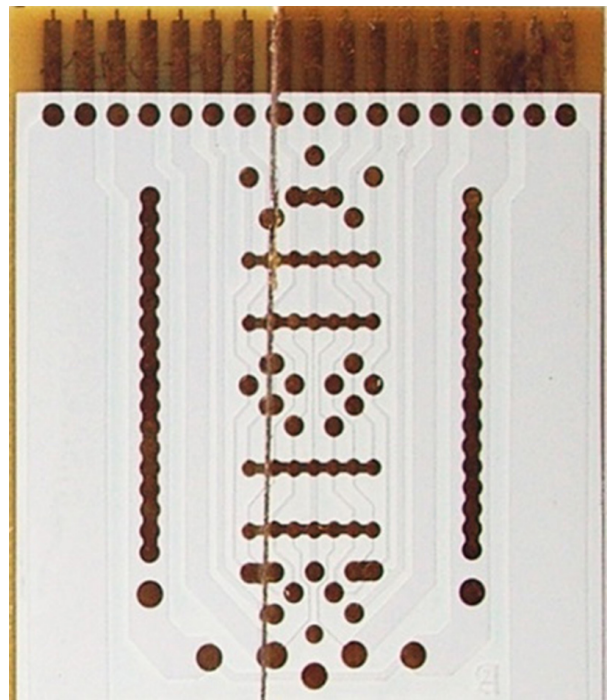
Techni AU Gold AT 8000

- Cyanide free process
- Up to 20 MTO bath life
- Reduced Nickel attack by 75%
- Sealed the surface and help balance thickness variation
- No Discoloration of white Solder Mask
- Minimal STD from pad to pad for enhanced cost and performance
- Self limiting

Note:

Technipad Au 6100 - Cyanide base process, is capable to work for ENEPIG, ENIG and EPIG.

Techni IM Gold AT 8000 - Cyanide free process, works at a slightly alkaline pH, and is not suitable for ENEPIG or EPIG.

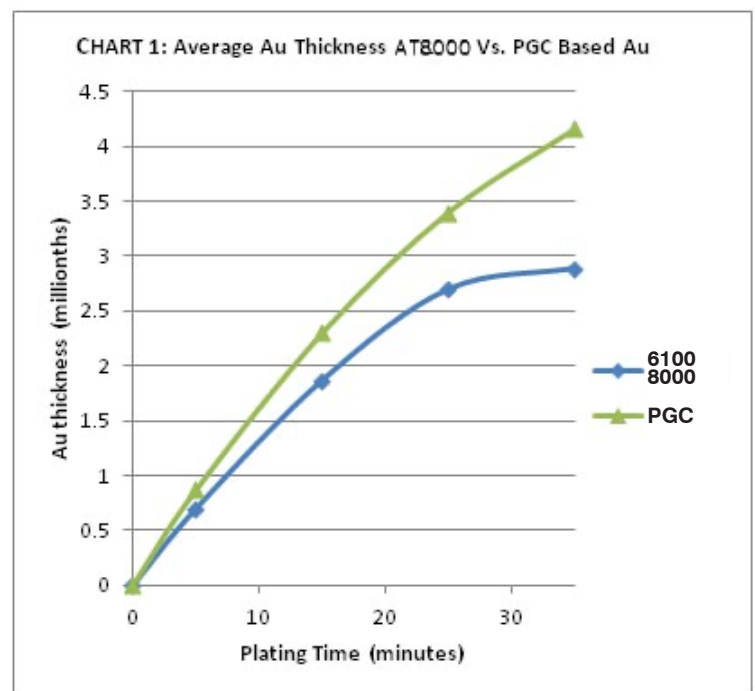


Before Reflow

After Reflow

No discoloration after reflow

Gold thickness AU6100/AT8000 VS Standard PGC bath



Self Limiting